



**Dr. Kangkana Baishya**

Designation: Assistant Professor (Contractual)

Qualification: PhD

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Area of Interest: VLSI Package Reliability Testing using Non-Destructive Techniques, Acoustic Image Processing/Image Processing

**List of Publications:**

**SCI Journals:**

1. "Failure pattern of solder joints identified through lifetime vibration tests", published in *Non Destructive Testing and Evaluation by Taylor and Francis*, 2022
2. "Investigation into how the floor plan layout of a manufactured PCB influences flip chip susceptibility to vibration", published in *IEEE Transactions on Components, Packaging and Manufacturing Technology*, 2020.

**SCI/Web of Science Indexed International Conferences:**

1. "Non-destructive Evaluation and Life Monitoring of Solder Joints in Area Array Packaging", 7<sup>th</sup> *IEEE Electronic System Integration Conference (ESTC)*, 2018.
2. "Toolbox for 3D Acoustic Imaging of Manufactured Electronics Circuits", 6<sup>th</sup> *IEEE Electronic System Integration Conference (ESTC)*, 2016.
3. "Real World Modelling of Circuit Board assemblies to help Inform Prognostic Predictions", 6<sup>th</sup> *IEEE Electronic System Integration Conference (ESTC)*, 2016.